



Material Content Data Sheet



Sales Product Name		BSC046N02KS G		Issued		24. January 2018		
MA#		MA001273780						
Package		PG-TDSON-8-1		Weight*		120.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.840	1.53	1.53	15273	15273
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		314	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	copper	7440-50-8	37.762	31.34	31.38	313419	313827
wire	non noble metal	copper	7440-50-8	0.046	0.04	0.04	380	380
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		703	
	plastics	epoxy resin	-	6.010	4.99		49886	
	inorganic material	silicondioxide	60676-86-0	36.232	30.07	35.13	300719	351308
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	12048	12048
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1374	1374
solder	noble metal	silver	7440-22-4	0.047	0.04		394	
	non noble metal	tin	7440-31-5	0.038	0.03		315	
	non noble metal	lead	7439-92-1	1.813	1.50	1.57	15044	15753
CLIP plating	noble metal	silver	7440-22-4	1.289	1.07	1.07	10702	10702
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		94	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.40	9.41	93955	94077
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		185	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.50	18.53	185017	185258
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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